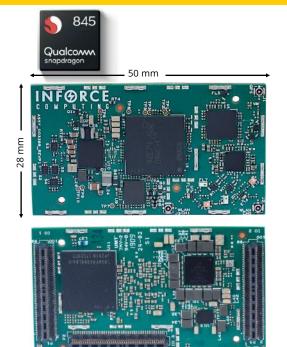






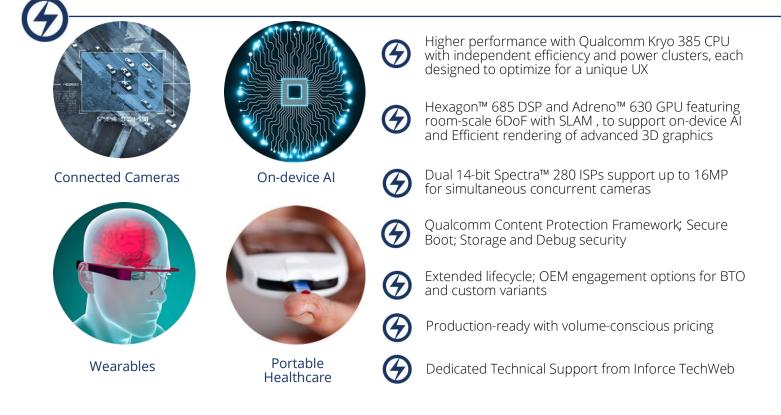
Qualcomm® Snapdragon™ 845 Processor based System-on-Module

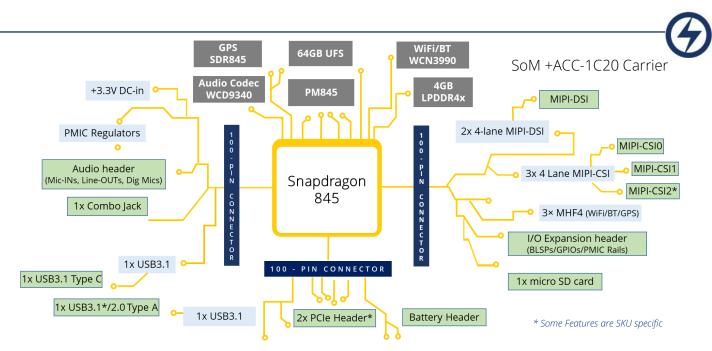


A compact compute module featuring on-device AI and Immersion for Embedded Applications

The Inforce 67X1 SoM is a small compute module that integrates Qualcomm[®]Kryo[™] 385 CPU, Adreno[™] 630 GPU, Hexagon[™] 685 DSP, Spectra[™] 280 camera ISP and Qualcomm's 3rd generation AI-Engine. This enables optimized AI performance for a more responsive, power-efficient user-experience and capture of cinema-grade videos in UHD@60fps resolution.

These components, coupled with 2x2 802.11ac Wi-Fi, BT 5.x, a full featured USB-C interface with UHD display capability and high fidelity audio make the Inforce 67X1 SoM a perfect fit for applications that necessitate on-device AI and immersive multimedia experiences. Optional SKUs support extended operating temperature range and EMI shielding for better RF noise protection, while also doubling up as a medium for heat spreading and dissipation to further improve performance.





Technical Specifications

Processors

- Custom 64-bit Kryo Octocore ARM® V-8 compliant CPU (SDA845 SoC) @2.8/1.8GHz each
- Qualcomm® Adreno™ 630 GPU with support for OpenGL ES 3.2, Vulkan 2 and OpenCL
- Qualcomm[®] Hexagon[™] 685 DSP with dual-HVX512 for ultra lowpower audio processing

Memory / Storage

- ♦ 4GB LPDDR4 RAM/64GB UFS
- ◆ SD V3.0 µSD card interface
- 2x USB 3.1 interfaces off which one is USB-C (USB 3.1/Gen1)

Connectivity

- 802.11n/ac MU-MIMO WiFi and BT/LE 5.x via WCN3990
- GPS/GLONASS via SDR845
- 1x 1-lane PCIe Gen 2 and 1x 1-lane PCIe Gen 3

Multimedia

- DP Alternate Mode on USB-C for 4K-DCI@24fps display
- Concurrent 4K60 10b encode + 4K60 10b decode
- Dual 4-lane MIPI-CSI lines for HEVC capture @4K60

Software

- Android 9 BSP pre-loaded wth Hexagon/SNPE/OpenCV SDKs enabled
- Debian Linux BSP

Carrier Board For Inforce 67X1 SoM



 ACC1C20 - A small but complete carrier that brings out all native interfaces of the SDA845 processor including USB-C to help create and optimize your products with the shortest turnaround time.

Other Specifications

- Power: +3.8V/6A Input
- Operating Temp: Commercial grade
- Relative Humidity: 5 to 95% non-condensing
- RoHS and WEE compliant

Ordering Info

Part Number	Description
◆ IFC6701-00-P1	Micro SoM (Android Pie OS); 2x B2B conn; Commercial Temp support (0º - 70ºC)
◆ IFC67A1-00-P1*	Micro SoM (Android Pie OS); 3x B2B conn; Commercial Temp support (0º - 70ºC)
◆ SYS6701-00-P1	IFC6701-00-P1 SoM based Ref Design
◆ SYS67A1-00-P1*	IFC67A1-00-P1 SoM based Ref Design

* - BTO SKU. MOQ of 100

SMART Wireless Computing® is a supplier of application-ready embedded hardware platforms in eco-aware, low-profile footprints, available off-the-shelf to serve growing markets enabled by the next generation of connected devices. At SMART, we are inspired by the inflection point in mobile and wireless technologies which is spawning innovative devices, content, and services. Together with silicon, software, and system partners, SMART is pioneering products with an optimized delivery model for target markets such as connected cameras, connected displays and connected fitness.



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